Product Change Notification / JAON-01KOJO966

Date:

03-Nov-2021

Product Category:

Battery Management and Fuel Gauges - Battery Chargers, Switching Regulators

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4912 Final Notice: Qualification of a new lead frame with 68x94 mils lead frame paddle size for selected MCP1653, MCP73833, MCP73834, MCP73837, and MCP73838 device families available in 10L MSOP (3x3mm) package assembled at NSEB assembly site.

Affected CPNs:

JAON-01KOJO966_Affected_CPN_11032021.pdf
JAON-01KOJO966_Affected_CPN_11032021.csv

Notification Text:

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of a new lead frame with 68x94 mils lead frame paddle size for selected MCP1653, MCP73833, MCP73834, MCP73837, and MCP73838 device families available in 10L MSOP (3x3mm) package assembled at NSEB assembly site.

Pre and Post Change Summary:

		Pre Change	Post Change
Assembly Site		UTAC Thai Limited (UTL-1) LTD (NSEB)	UTAC Thai Limited (UTL-1) LTD (NSEB)
Wire Material		Au	Au
Die Attach Material		8200T	8200T
Molding Compound Material		G600	G600
Lead Frame Material	Material	C7025	C7025
	Paddle Size	82x94 mils	68x94 mils
	Lead lock	No	Yes
		See Pre and Post change comparison	

Impacts to Data Sheet: None

Change Impact None

Reason for Change: To improve manufacturability by qualifying a new lead frame with 68x94 mils lead frame paddle size.

Change Implementation Status: In Progress

Estimated First Ship Date: November 28, 2021 (date code: 2149)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	November 2021				
Workweek	45	46	47	48	49
Qual Report Availability	X				
Final PCN Issue Date	X				
Estimated Implementation Date					X

Method to Identify Change: Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: November 3, 2021: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_JAON-01KOJO966_Pre and Post Change Summary.pdf
PCN_JAON-01KOJO966_Qual Report 1 of 2.pdf
PCN_JAON-01KOJO966_Qual Report 2 of 2.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

MCP1653R-E/UN
MCP1653S-E/UN
MCP1653RT-E/UN
MCP1653ST-E/UN
MCP73833-6SI/UN
MCP73833-AMI/UN
MCP73833-B6I/UN
MCP73833-BZI/UN
MCP73833-CNI/UN
MCP73833-FCI/UN
MCP73833-G8I/UN
MCP73833-GPI/UN
MCP73833-NVI/UN
MCP73833-YAI/UN
MCP73834-6SI/UN
MCP73834-B6I/UN
MCP73834-CNI/UN
MCP73834-FCI/UN
MCP73834-G8I/UN
MCP73834-GPI/UN
MCP73834-NVI/UN
MCP73834-YAI/UN
MCP73833T-6SI/UN
MCP73833T-AMI/UN
MCP73833T-B6I/UN
MCP73833T-BZI/UN
MCP73833T-CNI/UN
MCP73833T-FCI/UN
MCP73833T-G8I/UN
MCP73833T-GPI/UN
MCP73833T-NVI/UN
MCP73833T-YAI/UN
MCP73834T-6SI/UN
MCP73834T-B6I/UN
MCP73834T-CNI/UN
MCP73834T-FCI/UN
MCP73834T-G8I/UN
MCP73834T-GPI/UN
MCP73834T-NVI/UN
MCP73834T-YAI/UN
MCP73837-FCI/UN
MCP73837-FJI/UN
MCP73837-NVI/UN
MCP73838-AMI/UN
MCP73838-FCI/UN
MCP73838-FJI/UN

MCP73838-NVI/UN

MCP73837T-FCI/UN

MCP73837T-FJI/UN

MCP73837T-NVI/UN

MCP73838T-AMI/UN

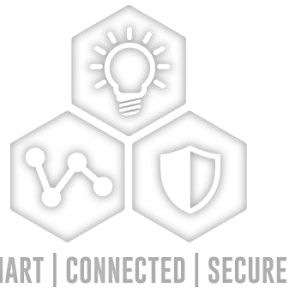
MCP73838T-FCI/UN

MCP73838T-FJI/UN

MCP73838T-NVI/UN

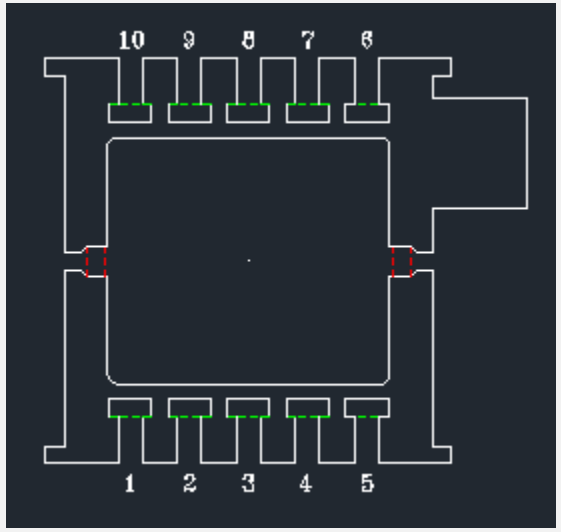
CCB 4912
Pre and Post Change Summary
PCN#: JAON-01KOJO966

A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



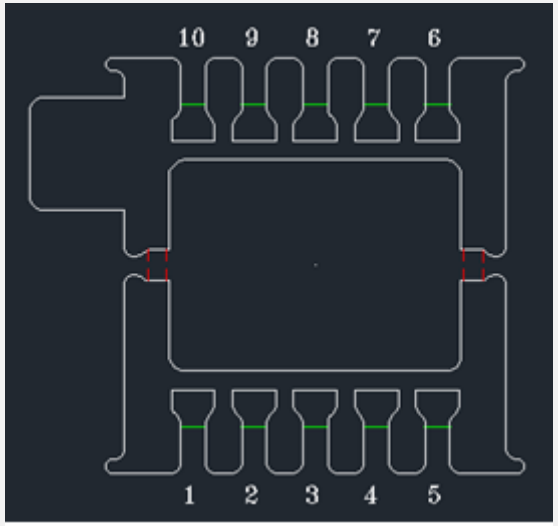
Lead frame comparison

Pre change NSEB



Lead frame material	C7025
Lead frame Paddle Size	82x94 mils
Lead frame Lead Lock	No

Post Change NSEB



Lead frame material	C7025
Lead frame Paddle Size	68x94 mils
Lead frame Lead Lock	Yes

QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: JAON-01KOJO966

Date:
June 14, 2016

Qualification of a new lead frame for HV9805MG-G catalog part number (CPN) available in 10L MSOP (3x3mm) package assembled at NSEB assembly site. The qualification of a new lead frame with 68x94 mils lead frame paddle size for selected MCP1653, MCP73833, MCP73834, MCP73837, and MCP73838 device families available in 10L MSOP (3x3mm) package assembled at NSEB assembly site will qualify by similarity (QBS).

PACKAGE QUALIFICATION REPORT

Purpose	Qualification of a new lead frame for HV9805MG-G catalog part number (CPN) available in 10L MSOP (3x3mm) package assembled at NSEB assembly site. The qualification of a new lead frame with 68x94 mils lead frame paddle size for selected MCP1653, MCP73833, MCP73834, MCP73837, and MCP73838 device families available in 10L MSOP (3x3mm) package assembled at NSEB assembly site will qualify by similarity (QBS).
CN	BC161017
QUAL ID	Q16048 rev A
MP CODE	VABA1YE3XA00
Part No.	HV9805MG-G
Bonding No.	A-053196 Rev. B
CCB No.	2503 and 4912
Package	
Type	10L MSOP
Package size	3x3 mm
Lead Frame	
Paddle size	68 x 94 mils
Material	C7025
Surface	Spot Ag Plated
Process	Stamped
Lead Lock	Yes
Part Number	FM0008
Treatment	None
Die attach material	
Epoxy	2200D
Wire	Au wire
Mold Compound	G600
Plating Composition	Matte Tin

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
NSEB164100001.000	TSMC915451595.000	1601H4R
NSEB164100002.000	TSMC915451595.000	1601H4V
NSEB164100003.000	TSMC915451595.000	1601H55

Result [X] Pass [ ] Fail [ ] _____

10L MSOP (3x3mm) assembled by UTL (NSEB) pass reliability test per QCI-39000.This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020D standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020D)	IPC/JEDEC J-STD-020D	135	0/135	Pass	

<u>Precondition Prior Perform Reliability Tests</u> (At MSL Level 1)	**Electrical Test :**+25°C System: TMT_HV_NT	JESD22-A113	693(0)	693		Good Devices
	Bake 150°C, 24 hrs System: CHINEE			693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test :+25°C System: TMT_HV_NT			0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	**Stress Condition:** -65°C to +150°C, 500 Cycles System : TABAI ESPEC TSA-70H	JESD22-A104		231		Parts had been pre-conditioned at 260°C
	Electrical Test: + 25°C System: TMT_HV_NT		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (> 4.0 grams)		15 (0)	0/15	Pass	
	Bond Shear (>20.00 grams)		15 (0)	0/15	Pass	
UNBIASED-HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: TMT_HV_NT		231(0)	0/231	Pass	77 units / lot
HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. **Bias Volt:** 5.0 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test:+25°C System: TMT_HV_NT		231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 504 hrs System: SHEL LAB	JESD22-A103		45		45 units
	Electrical Test :+25°C System: TMT_HV_NT		45(0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Solderability **Temp 215°C**	**Steam Aging:** Temp 93°C,8Hrs System: SAS-3000 Solder Dipping: Solder Temp.215°C Solder material: SnPb Sn63,Pb37 System: ERSA RA 2200D Visual Inspection: External Visual Inspection	JESD22B-102E	22 (0)	22 22 0/22	Pass	
Solderability **Temp 245°C**	**Steam Aging:** Temp 93°C,8Hrs System: SAS-3000 Solder Dipping:Solder Temp.245°C Solder material:Pb Free Sn 95.5Ag3.9 Cu0.6 System: ERSA RA 2200D Visual Inspection: External Visual Inspection	JESD22B-102E	22 (0)	22 22 0/22	Pass	
Physical **Dimensions**	Physical Dimension, 30 units from 1 lot	JESD22-B100/B108	30(0) Units	0/30	Pass	
Bond Strength **Data Assembly**	Wire Pull (> 4.0 grams) Bond Shear (>20.00 grams)	M2011 JESD22-B116	30 (0) Wires 30 (0) bonds	0/30 0/30	Pass Pass	